

e.

CY WIRELESS TECHNOLOGY LIMITED

SPECIFICATION FOR APPROVAL

CUSTOMER				
NOMINAL FREQUENCY	13.5268MHz			
HOLDER TYPE	3225			
SPEC. NO. (P/N)	13.52688			
CUSTOMER P/N				
ISSUE DATE	Apr. 17, 2019			

Add: 1407, Block C, Tairan Building, 8th Tairan Road, Futian District, Shenzhen, Guangdong, China TEL: 0086-755-23937707 FAX: 0086-755-88351759 www.rficy.com

1. ELECTRICAL SPECIFICATIONS

Parts Number : <u>13.5268S3</u>

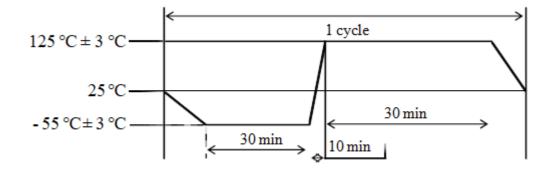
T4 and	Symbol	Specifications			N. (
Item		Min	Туре	Max	Units	Notes
Nominal frequency	FO	13.5268		MHz		
Mode of Oscillation	ОТ	Fundamenta			al	
Load Capacitance	LC	10		pF		
Frequency Tolerance	FT	± 10		ррт	at 25℃± 3℃	
Frequency Stability		± 20		ppm	with working temperature Reference to 25°C	
Working temperature range	TR	-40~85		°C		
Drive Level	DL	100		μW	Max.	
Series Resonant Resistance R	R CI/RR	≤60		Ω	Max.	
Insulation Resistance	IR	>500		MΩ		
Shunt Capacitance C0	C0	5		pF		
Aging			3		ppm/yr.	
Storage temperature range		-	55 ~ 12	25	°C	
Unit Weight					g	

2. MARKING

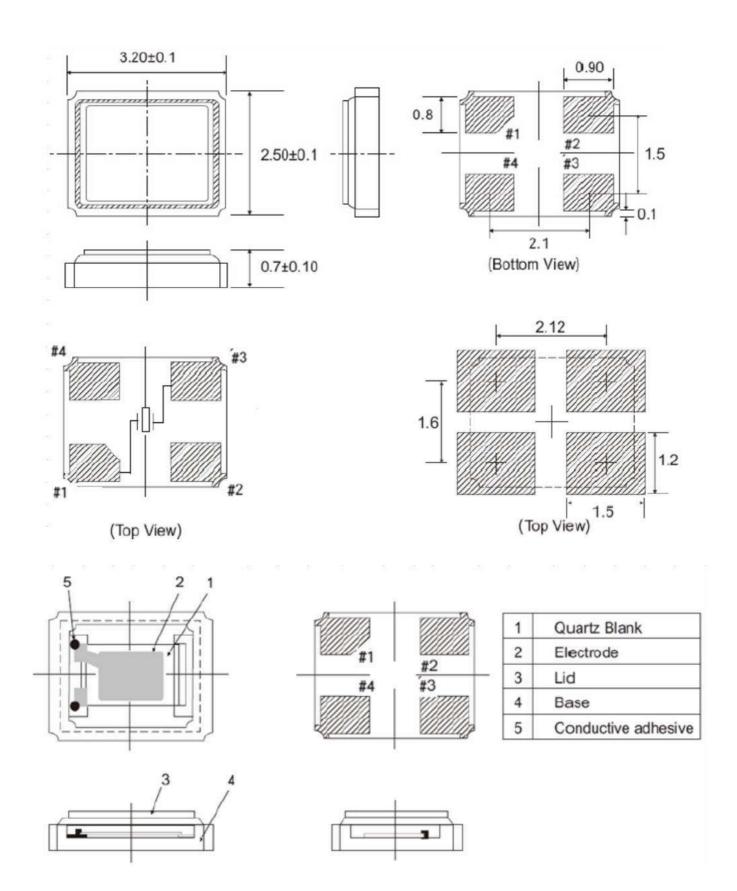
13.5268S3

3. RELIABILITY SPECIFICATIONS

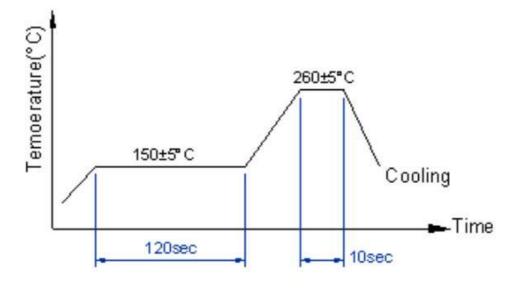
NO	TEST ITEM	TEST METHODS			
1	DROP TEST	Device are dropped from a height of 150 cm onto 2 mm thickness stainless plate executing 3 times of random drops.			
2	MECHANICAL SHOCK	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times.			
		Frequency range	10 ~ 2000 Hz		
		Amplitude	1.5 mm		
3	3 VIBRATION	Sweep Time	20 minute		
		Test Time	2 hours		
		MIL - STD - 20E Method 208C			
		Temperature	245°C±5°C		
		Material	H63A (Silver 2 ~ 3 %)		
4	SOLDERABILITY	Immersion depth	0.5 mm minimum		
		Immersion time	3 ± 0.5 seconds		
		Flux	Rosin resin methyl alcohol		
			solvent (1:4)		
5	RESISTANCE TO	MIL - SLD -202, Method 210, Condition I or J			
	SOLDERING HEAT	10 sec immersion into 260 ± 5 °C solder pot, above			
		180°C is 90 ~ 120 sec.			
6	LOW TEMP. STORAGE	Leave at - 55 °C \pm 2°C for 1000 \pm 12 hours			
7	HIGH TEMP. STORAGE	Leave at 125 °C \pm 2°C for 1000 \pm 12 hours			
8	THERMAL SHOCK	Total 100 cycles of the following temperature cycle			



4. **DIMENSIONS**

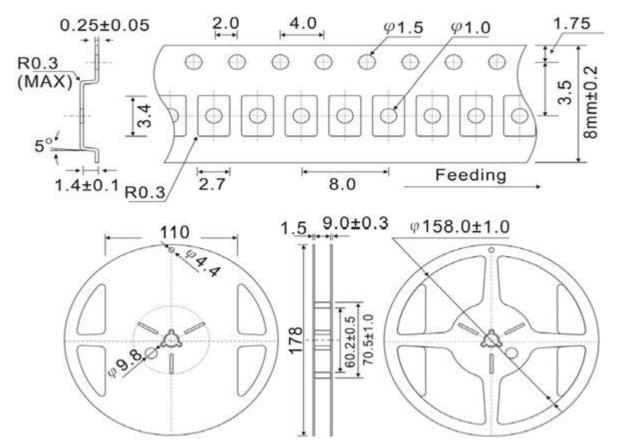


5. SUGGESTED IR REFLOW PROFILE



Total Time: 200 Sec.Max Solder melting point : 185°C

6. PACKING



1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.

2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

